THINK ON.

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Depth and Intensity LiDAR imaging with Pandion SPAD array

International SPAD Sensor Workshop 2020

Public Information



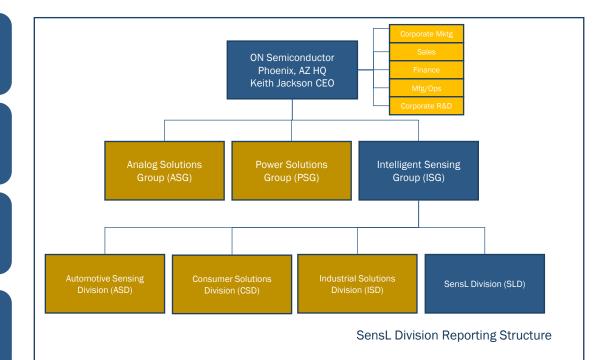
SensL Division (SLD) of ISG

SensL acquired by ON Semiconductor May 2018

Independent division within Intelligent Sensing Group (ISG) focused on LiDAR solutions

Division engineering remains in Cork Ireland

Leveraging resources of all 34,000 ON employees





World HQ Phoenix, AZ USA



ISG HQ Santa Clara, CA USA

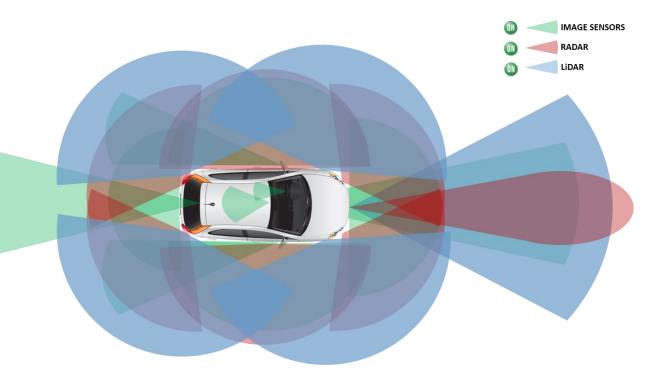


SensL Division HQ Cork, Ireland



ADAS/AD: A Fusion of Sensors

- Definition:
 - Provide color/intensity, depth, velocity for every point/kernel in scene in all conditions
- Benefit:
 - Drive higher confidence decisions from perception algorithm through redundancy and existence of multiple modalities with unique advantages



- "Sensor fusion is key because the more complex features get, the more redundancy you need. Every autonomous vehicle is going to have some combination of LiDAR, Radar and camera."
 ADAS engineer at prominent OEM, <u>Beyond the headlights: Woodside Capital Partners</u>
- ISO26262 ASIL D means that a backup system must be ready to take over in case of system failure
- ASIL D system rating means higher complexity due to the safety requirements.
 - ASIL levels are often decomposed to lower ratings for the components (e,g. ASIL B in an ASIL D system)

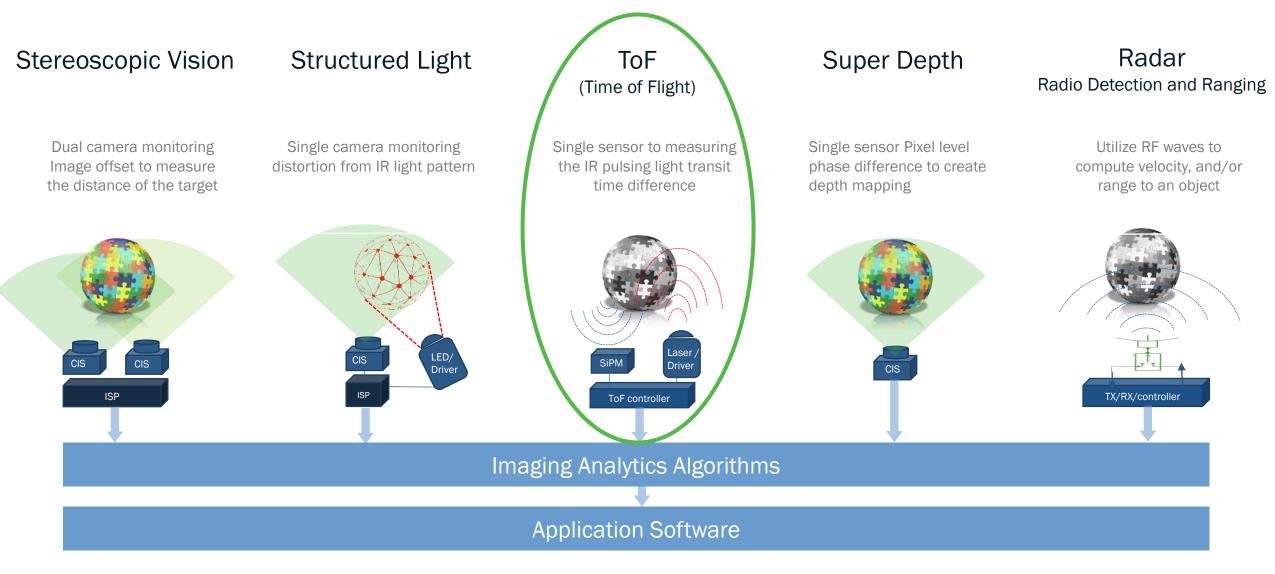


Sensor Performance Comparison

	· · · · ·			
		RADAR		
Angular Resolution				
Depth Resolution				
Velocity				
Depth Range				
Traffic Signs				
Object Edge Precision				
Lane Detection				
Color Recognition				
Adverse Weather				
Low-Light Performance				
Cost				
			'	
Sensor Fusion for ADAS/AD				



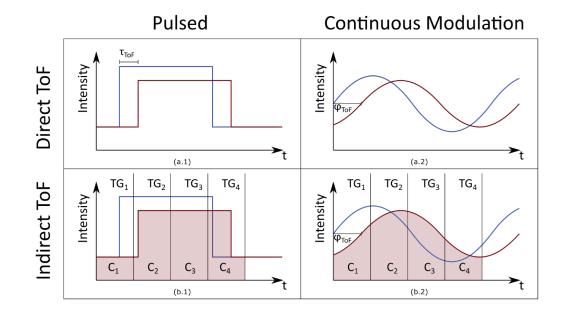
Depth Mapping – Techniques – Time of Flight





Introduction – LiDAR with SPAD-based Sensors

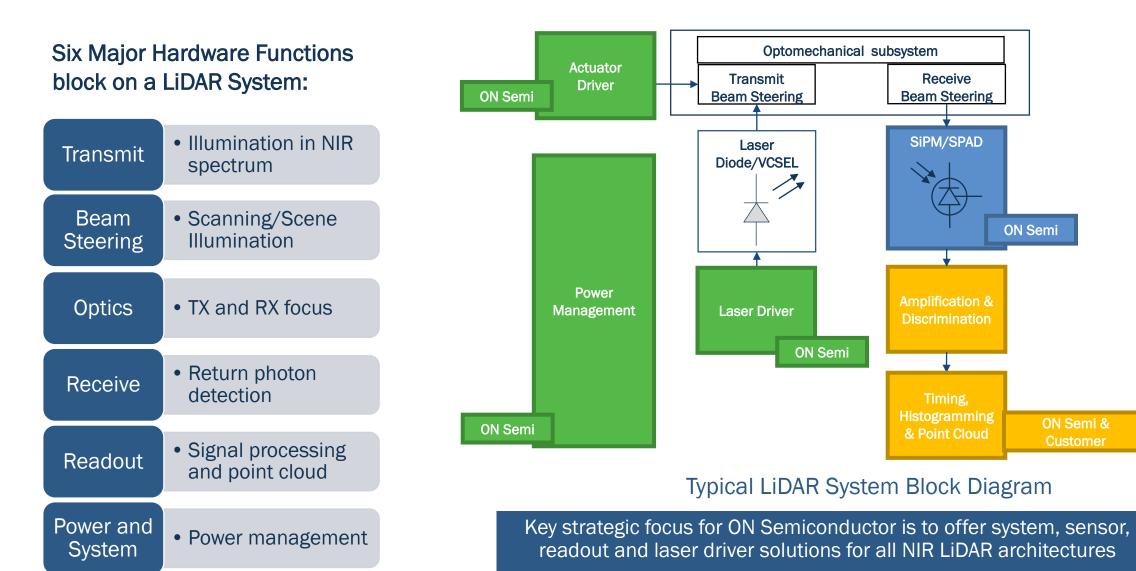
- Principle: direct Time-of-Flight (dToF)
 - Time interval between controlled light emission and echo(es) detection
 - Phase domain \rightarrow continuous dToF
 - Time domain \rightarrow pulse dToF
 - Power efficient
 - Key benefits
 - Multiple echoes
 - Shot noise limited
 - High timing precision
- Single Photon Avalanche Diode (SPAD)
 - Single photon sensitivity
 - Fast and precise timing response
 - SPAD arrays and silicon photomultipliers array (SiPM)
 - Statistical behaviour (TCSPC)





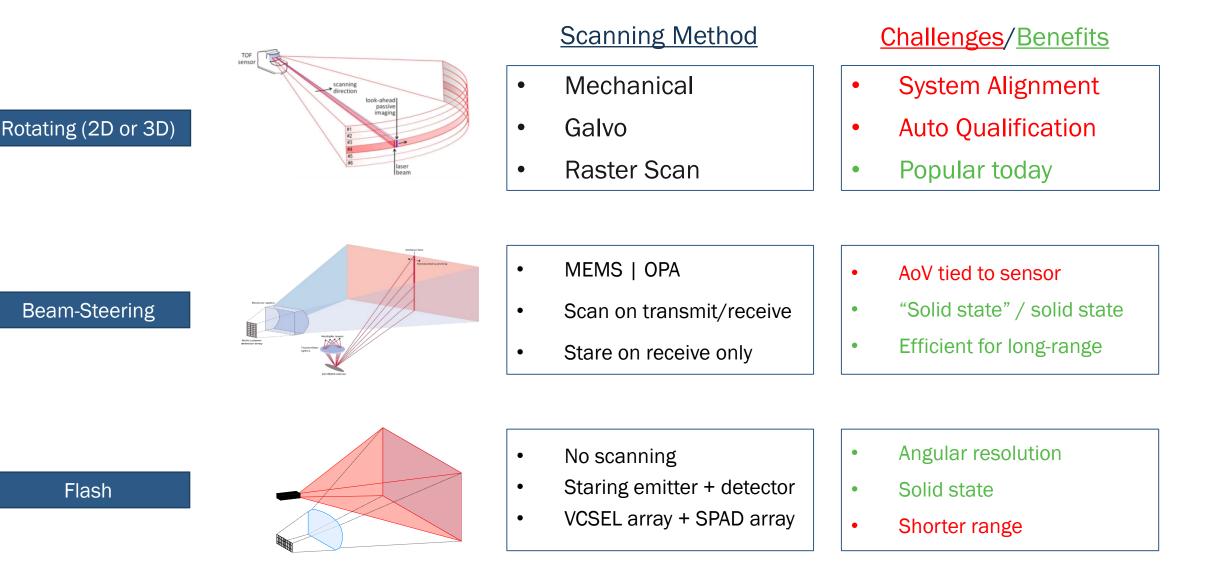


LiDAR Function Blocks



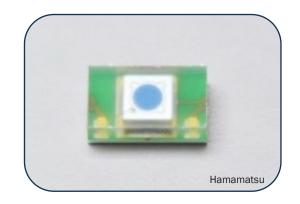


LiDAR Scene Illumination & Detection Methodologies



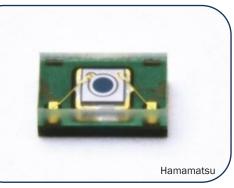


Types of Photodetectors for LiDAR





Low Voltage
 Good Uniformity
 No Gain
 Market Adoption

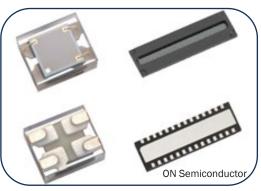


Avalanche Photodiodes & APD Arrays

- High Voltage
 Poor Uniformity
 Moderate Gain (10²)
- 🔌 Market Adoption



Low Voltage
 Excellent Uniformity
 n/a (Geiger Mode)
 Market Adoption



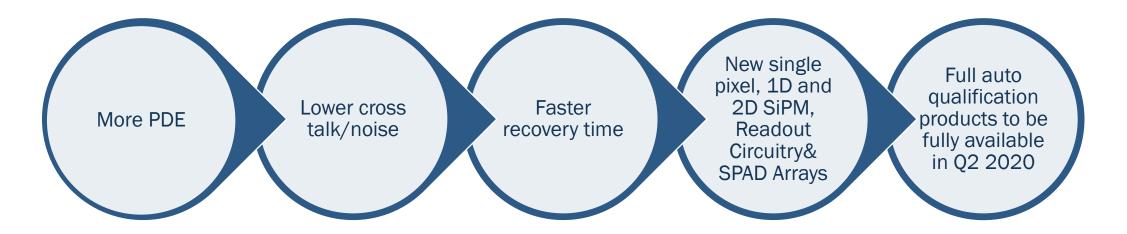
Silicon Photomultipliers & SiPM Arrays

- Low Voltage
- Excellent Uniformity
- Very High Gain (10⁶)
- Market Adoption

Higher Performance Detector = Better Ranging Performance



What is New on Detector Horizon?



SYSTEM BENEFIT:

Longer Range OR Less Laser Power



SPAD Arrays for LiDAR

Improved angular resolution

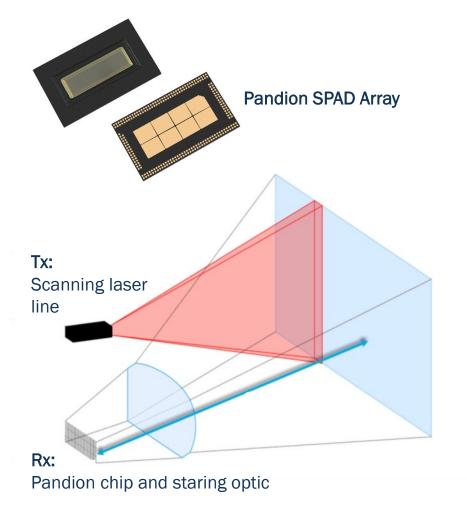
 Higher density pixels = higher resolution & more point cloud details

Better ambient light rejection

• <5ns recovery time = less dead time

Flexibility for low cost system design

- Flash for short range (<15m)
- Scanning for long range

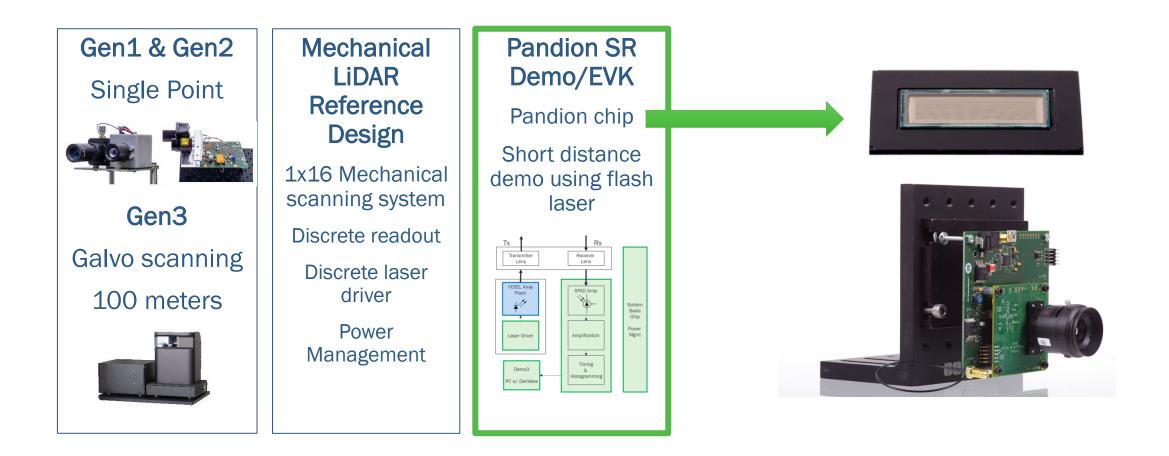


Example SPAD Array Architecture

Wide range of markets from automotive to consumer

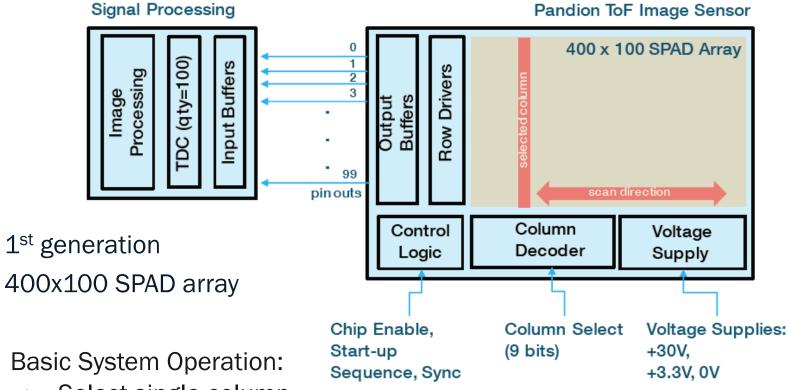


LiDAR Reference Design & Demonstrator Plans





Pandion Application Block Diagram



ARRAY SPECIFICATIONS

Parameter ¹	Value	
Number of pixels	40,000	
Array configuration	400 x 100	
Array size	15.44 mm x 3.86 mm	
SPAD size	31.9 μm x 12.1 μm	
Pixel size	38.6 µm x 38.6 µm	
Fill Factor	26 %	
Photon detection probability @ 905 nm	~2 %	
Temperature coefficient of Vbr	21.5 mV/°C	

- Basic System Operation:
 - Select single column ۲
 - Fire laser
 - Timestamp 100 signals with off-chip • TDC
 - Scan laser and repeat for next column ۲
 - Only one column is enabled for exposure/read at a time

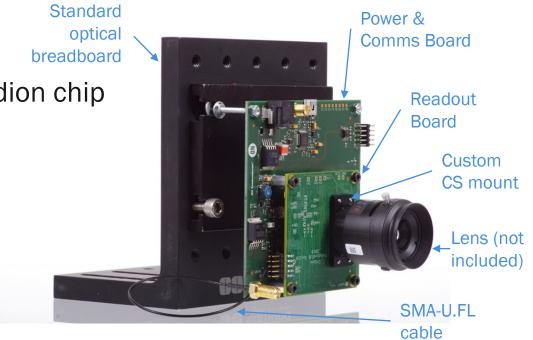


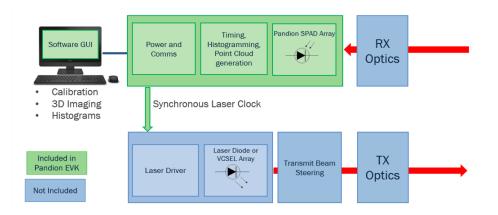


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Pandion EVK Details

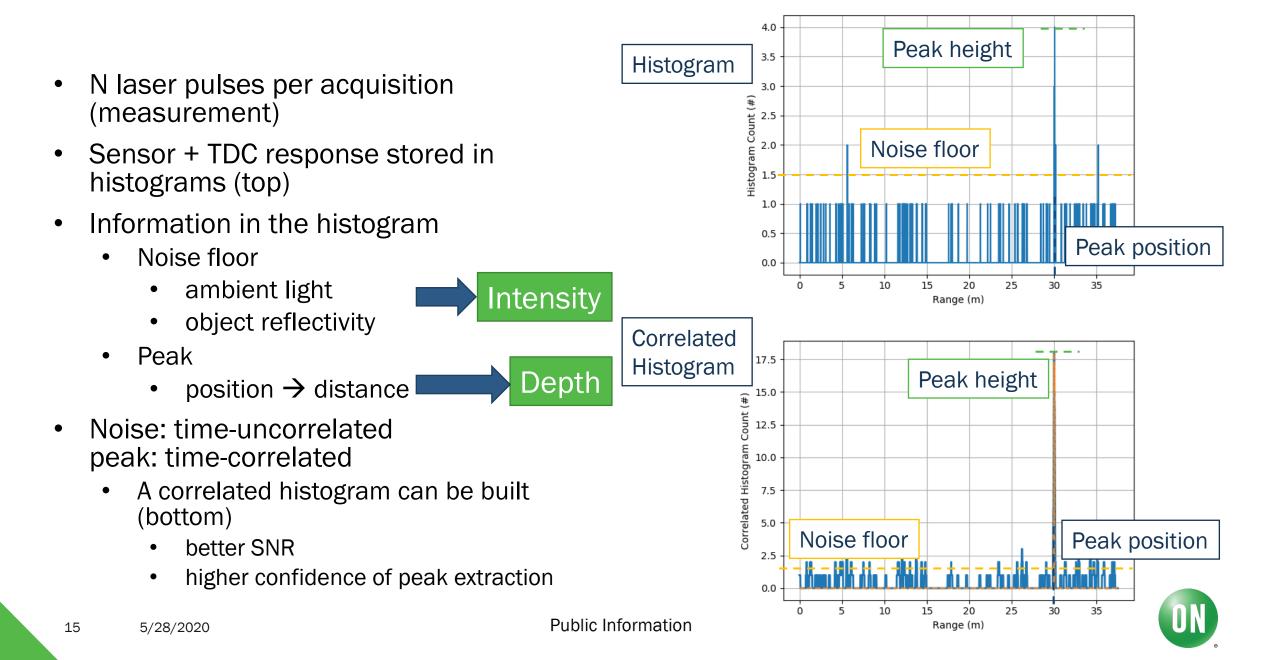
- Plug-and-play system for quick evaluation of the Pandion chip
- The Pandion EVK contains:
 - Readout Board
 - Pandion chip
 - FPGA based TDC
 - Power & Communications Board
 - Universal Power supply & cable
 - GUI
 - Lens mount for CS lens
 - User Manual
- Additional Requirements for ToF Imaging
 - Detector Optics
 - Illumination source
 - Laser clock signal available on comms board for sync
 - U.FL compatible cable to connect laser clock
 - E.g. SMA to U.FL cable (<u>digikey link</u>)
 - Alignment of Tx and Rx





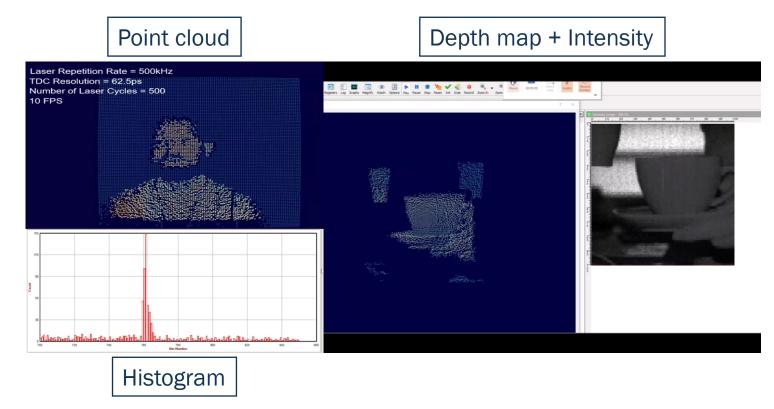


Pandion EVK Readout – Histogramming – Depth and Intensity



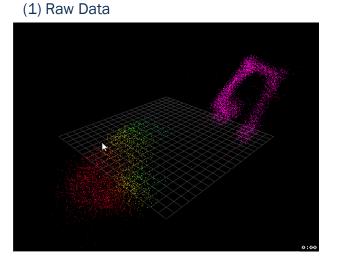
Pandion EVK – 3D and Intensity

- GUI can show
 - Depth point cloud
 - Individual pixel histograms
 - Intensity picture
- How?
 - FPGA generates and store histograms
 - Peak position \rightarrow depth map
 - Noise floor counts \rightarrow intensity
 - Software does 3D rendering

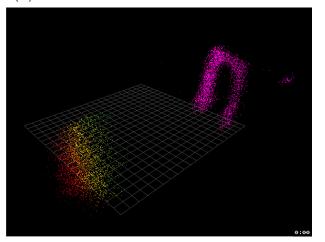




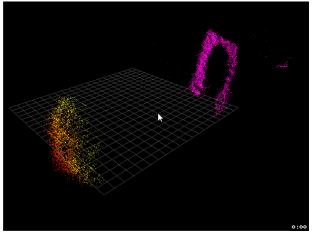
Data Rendering: Applying Filters to Pandion Point Cloud



(2) Subtraction of a Flat Wall



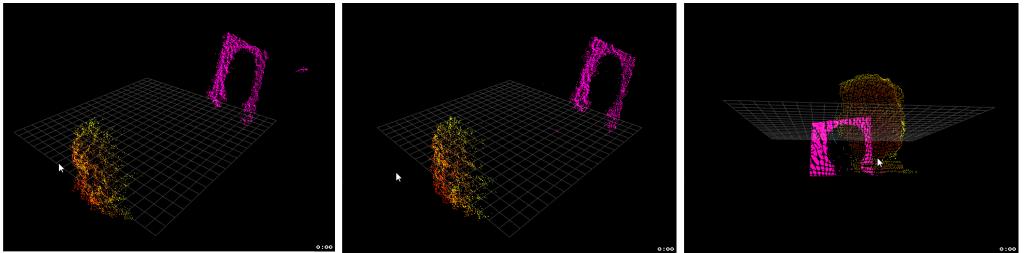
(3) + Spatial Bilateral Filter (Kernel size = 5)



(4) + Spatial Median Filter (Kernel size = 3)

(5) Remove Out of Bounds Pixels

(6) +Temporal 5 frame averaging





Public Information



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Final Slide

5/28/128020

Public Information



Appendix

